



Material Content Data Sheet



Sales Product Name		PXAC180602MD V1 R500		Issued		27. September 2017		
MA#		MA001346732						
Package		PG-HB1DSO-4-1		Weight*		1662.56 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.928	0.24	0.24	2363	2363
leadframe	inorganic material	phosphorus	7723-14-0	0.054	0.00		33	
	non noble metal	zinc	7440-66-6	0.216	0.01		130	
	non noble metal	iron	7439-89-6	4.323	0.26		2600	
wire	non noble metal	copper	7440-50-8	175.547	10.56	10.83	105588	108351
	noble metal	gold	7440-57-5	10.271	0.62	0.62	6178	6178
	encapsulation	organic material	carbon black	1333-86-4	1.804	0.11		1085
encapsulation	plastics	epoxy resin	-	70.347	4.23		42313	
	inorganic material	silicondioxide	60676-86-0	529.108	31.82	36.16	318248	361646
	leadfinish	noble metal	palladium	7440-05-3	0.263	0.02		158
plating	noble metal	gold	7440-57-5	0.230	0.01		139	
	non noble metal	nickel	7440-02-0	5.953	0.36	0.39	3581	3878
	noble metal	palladium	7440-05-3	0.359	0.02		216	
heatspreader	noble metal	gold	7440-57-5	0.315	0.02		189	
	non noble metal	nickel	7440-02-0	8.140	0.49	0.53	4896	5301
	inorganic material	phosphorus	7723-14-0	0.256	0.02		154	
*deviation	< 10%			850.595	51.16	51.23	511617	512283
Sum in total:						100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com